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PATENT

Atty. Dkt. No. APPM/003049.X1/CP/DT/PJS

IN THE SPECIFICATION:

Please replace paragraph [0033] with the following amended paragraph:

[0033] The flow of argon preferably ranges from about 5 to about 50 sccm, and the flow of helium/hydrogen preferably ranges from about 0 sccm to about 2000 sccm for 200 mm substrates. Chamber pressures are between about 1 mTorr and about 200 mTorr. The plasma treatment effectively cleans, ~~treat~~treats, and/or modifies the patterned surface in 10 to 150 seconds. After precleaning, a CVD or PVD metal layer is deposited on an optional liner or nucleation layer.